# 2SA893, 2SA893A

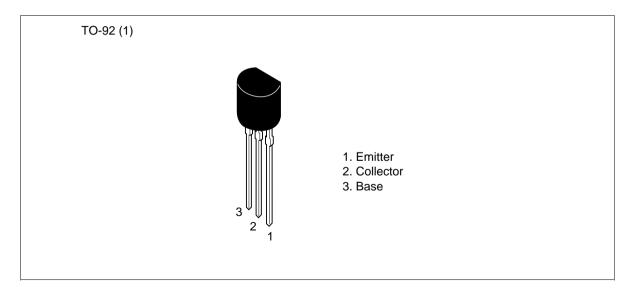
Silicon PNP Epitaxial

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#### Application

- Low frequency high voltage amplifier
- Complementary pair with 2SC1890/A

#### Outline





## 2SA893, 2SA893A

#### **Absolute Maximum Ratings** (Ta = $25^{\circ}$ C)

Item	Symbol	2SA893	2SA893A	Unit
Collector to base voltage	V <sub>CBO</sub>	-90	-120	V
Collector to emitter voltage	V <sub>CEO</sub>	-90	-120	V
Emitter to base voltage	V <sub>EBO</sub>	-5	-5	V
Collector current	I <sub>c</sub>	-50	-50	mA
Collector power dissipation	Pc	300	300	mW
Junction temperature	Tj	150	150	°C
Storage temperature	Tstg	-55 to +150	-55 to +150	°C

#### **Electrical Characteristics** (Ta = 25°C)

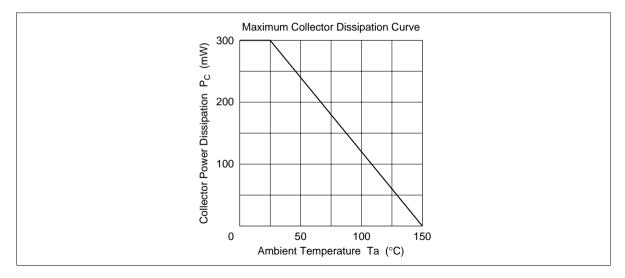
		2SA8	93		2SA893A				
Item	Symbol	Min	Тур	Мах	Min	Тур	Max	Unit	Test conditions
Collector to emitter breakdown voltage	$V_{\scriptscriptstyle (BR)CEO}$	-90	_	_	-120	_	_	V	$I_{c} = -1 \text{ mA}, \text{ R}_{BE} = \infty$
Collector cutoff current	I <sub>CBO</sub>	—	—	-0.5	—			μΑ	$V_{CB} = -75 \text{ V}, \text{ I}_{E} = 0$
		_	_	_	_	_	-0.5	μΑ	$V_{CB} = -100 \text{ V}, I_{E} = 0$
DC current transfer ratio	$h_{FE}^{*1}$	250	—	800	250	—	800		$V_{ce} = -12 \text{ V},$ $I_c = -2 \text{ mA}$
Base to emitter voltage	$V_{BE}$	_	_	-0.75	_	_	-0.75	V	$V_{ce} = -12 V,$ $I_{c} = -2 mA$
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	_	_	-0.5	_	_	-0.5	V	$I_{c} = -10 \text{ mA},$ $I_{B} = -1 \text{ mA}$
Gain bandwidth product	f <sub>T</sub>	_	120	—	_	120	_	MHz	$V_{ce} = -12 V,$ $I_{c} = -2 mA$
Collector output capacitance	Cob	—	1.8	—	—	1.8	—	pF	$V_{CB} = -25 \text{ V}, \text{ I}_{E} = 0,$ f = 1 MHz
Noise figure	NF	_	2	10	—	2	10	dB	$V_{cE} = -6 V,$ $I_c = -50 \mu A$ $R_g = 50 k\Omega, f = 1 kHz$
Note: 1. The 2SA893/A is grouped by $h_{FE}$ as follows. D E									

250 to 500 400 to 800

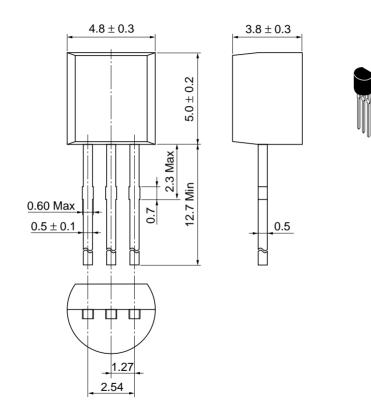
See characteristic curves of 2SA872 and 2SA872A

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### 2SA893, 2SA893A



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Hitachi Code	TO-92 (1)
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	0.25 g

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